

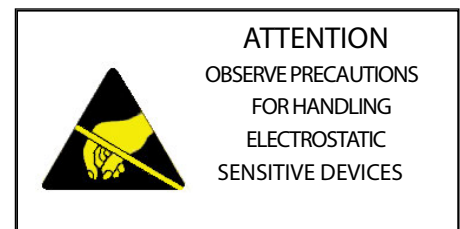
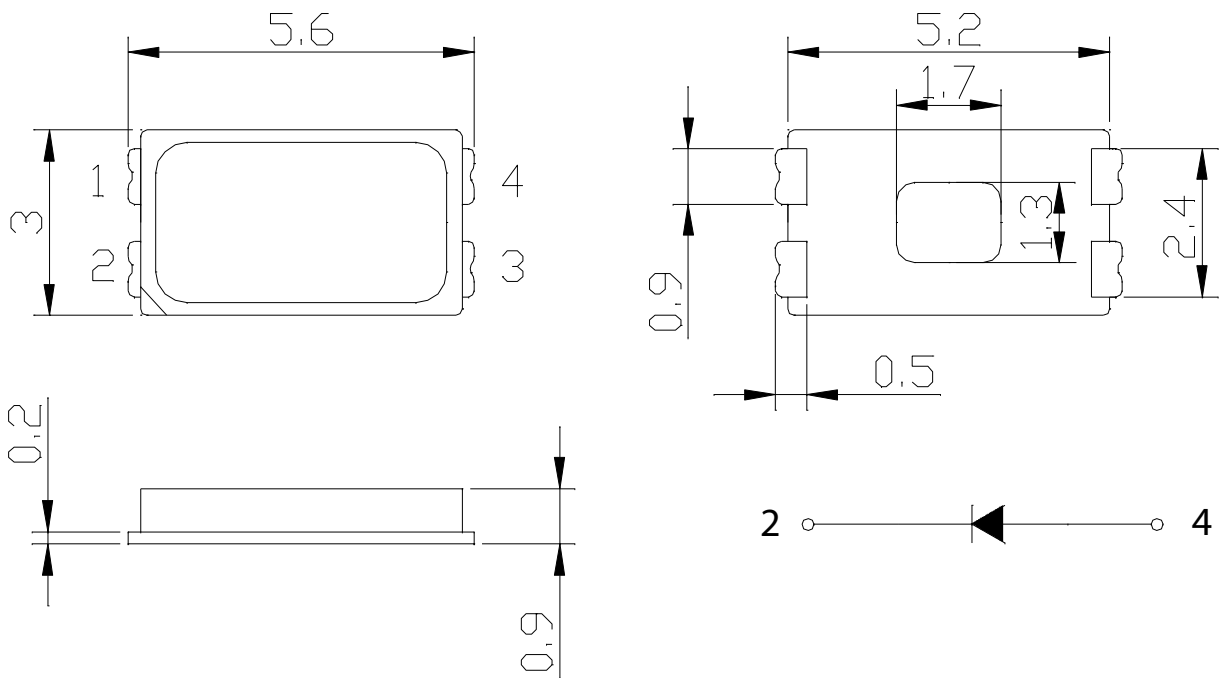
# TOP LED, 5630, Warm White

## Feature

- Viewing angle:120deg
- The materials of the LED dice is InGaN
- 5.6mm×3.0mm×0.9mm
- RoHS compliant lead free soldering compatible

CC-IMH5630DS-FE-J

## Package Outline



## NOTES:

1. All dimensions are in millimeters (inches);
2. Tolerances are  $\pm 0.2$ mm (0.008inch) unless otherwise noted.

Absolute maximum ratings at Ta=25°C

Parameter	Symbol	Value	Unit
Forward current	If	180	mA
Reverse voltage	Vr	5	V
Operating temperature range	Top	-20 ~ +85	°C
Storage temperature range	Tstg	-35 ~ +85	°C
Pulse Forward Current	Ifp	1000	mA
Electrostatic Discharge	ESD	2000(HBM)	V

Electro-optical characteristics at Ta=25°C

Parameter		Test Condition	Symbol	Value			Unit
				Min.	Typ.	Max.	
Forward voltage	Rank H1	If=150mA	Vf	3.0	--	3.1	V
	Rank H2			3.1	--	3.2	V
	Rank I1			3.2	--	3.3	V
	Rank I2			3.3	--	3.4	V
	Rank J1			3.4	--	3.5	V
	Rank J2			3.5	--	3.6	V
Luminous flux	Rank RCA	If=150mA	Φ	37	--	40.9	lm
	Rank RDA			40.9	--	45.3	lm
	Rank SAA			45.3	--	50	lm
	Rank SBA			50	--	55.3	lm
Viewing angle at 50% Iv		If=150mA	2 θ 1/2	--	120	--	Deg
Color Rendering Index		If=150mA	CRI	80	--	--	--
Reverse current		Vr=5V	Ir	--	--	10	μA

NOTE: (Tolerance: Iv ±10%, Vf ±0.05V, X, Y ±0.005)

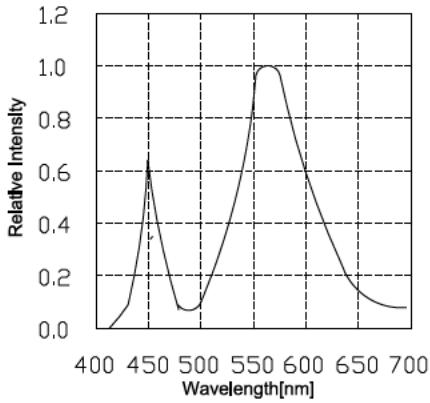
IFP Conditions: Pulse Width ≤10msec. and Duty ≤1/10.



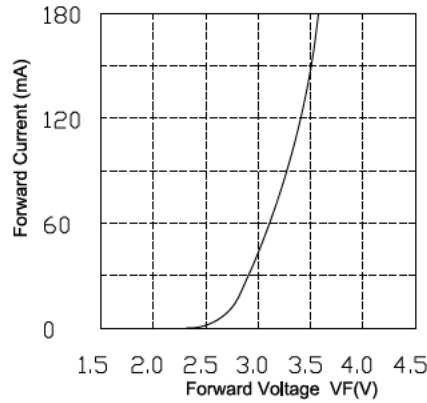
## Typical optical characteristics curves

### Spectral Distribution

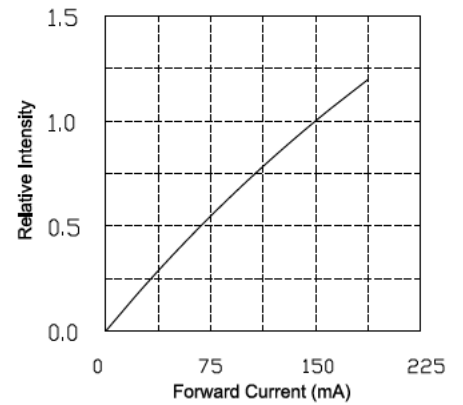
Relative Intensity vs. Wavelength (Ta=25°C)



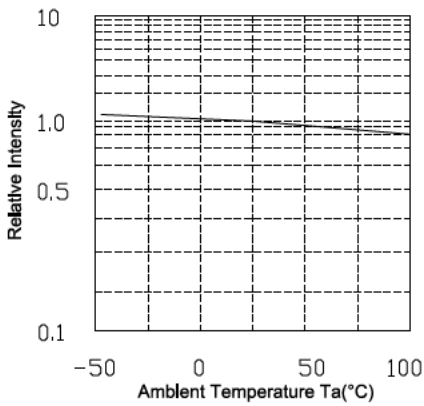
Forward Current vs. Forward Voltage (Ta=25°C)



Relative Intensity vs. Forward Current (Ta=25°C)

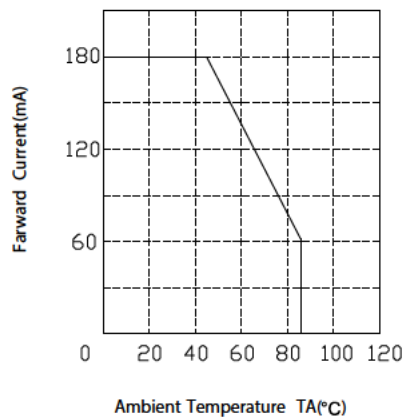


Relative Intensity vs. Ambient Temperature

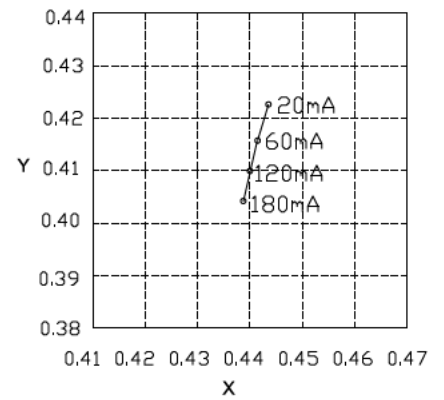


### Derating

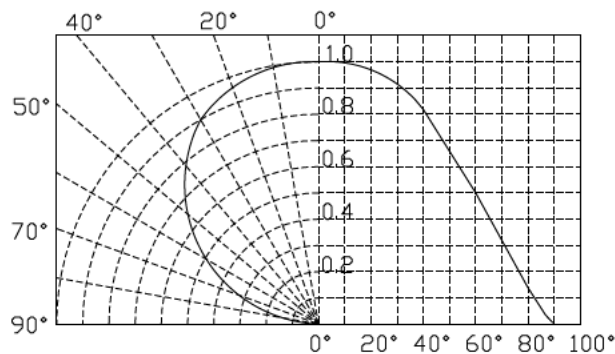
Maximum Forward Current vs. Ambient Temperature



Forward Current vs. Chromaticity (Ta=25°C)



### Diagram characteristics of radiation



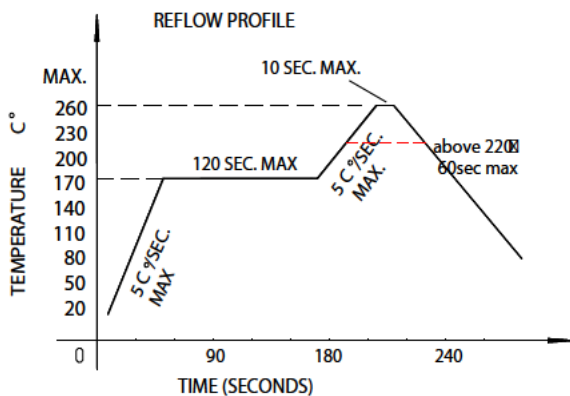
## Reflow profile

- Soldering condition
  - Recommended soldering conditions

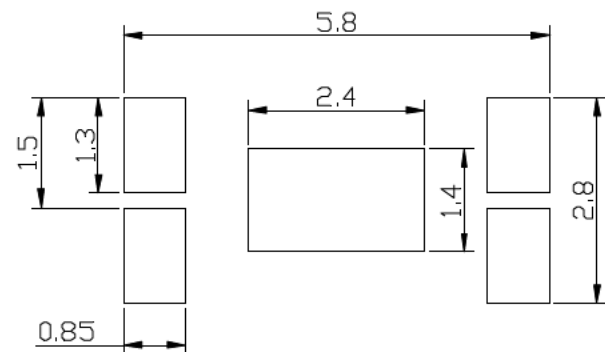
Reflow Soldering		Hand Soldering	
Pre-heat	160~180°C	Temperature	300°C Max.
Pre-heat time	120 seconds Max.	Soldering time	3 second Max. (one time only)
Peak temperature	260°C Max.		
Soldering time	10 seconds Max.		
Condition	Refer to Temperature-profile		

After reflow soldering rapid cooling should be avoided

- Temperature-profile (Surface of circuit board)  
Use the following conditions shown in the figure



## RECOMMEND PAD DESIGN (Units: mm)



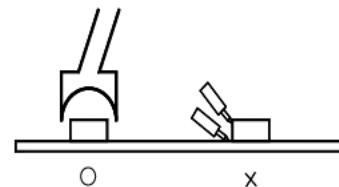
1. Reflow soldering should not be done more than two times
2. When soldering, do not put stress on the LEDs during heating

- Soldering iron

1. When hand soldering, keep the temperature of the iron under 300°C, and at that temperature keep the time under 3 sec.
2. The hand soldering should be done only a time
3. The basic spec is  $\leq 5$  sec. when the temperature of 260°C, do not contact the resin when hand soldering

- Rework

1. Customer must finish rework within 5 sec under 260°C
2. The head of iron can not touch the resin
3. Twin-head type is preferred.



## • CAUTIONS

The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be influence to the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when using the picking nozzle, the pressure on the silicone resin should be proper.

## Reliability

### (1) TEST ITEMS AND RESULTS

Type	Test Item	Ref. Standard	Test Conditions	Note	Number of Damaged
Environmental Sequence	Resistance to Soldering Heat(Reflow Soldering)	JESD22-B106	Tsld=260°C,10sec	2 times	0/22
	Temperature Cycle	JESD22-A104	-40°C 30min ↑↓ 5min 100°C 30min	300 cycle	0/22
	Thermal Shock	JESD22-A106	-40°C 15min ↑↓ 100°C 15min	300 cycle	0/22
	High Temperature Storage	JESD22-A103	T <sub>a</sub> =100°C	1000 hrs	0/22
	Low Temperature Storage	JESD22-A119	T <sub>a</sub> =-40°C	1000 hrs	0/22
Operation Sequence	Life Test	JESD22-A108	T <sub>a</sub> =25°C I <sub>F</sub> =150mA	1000 hrs	0/22
	High Humidity Heat Life Test	JESD22-A101	60°C RH=90% I <sub>F</sub> =150mA	1000 hrs	0/22

### (2) CRITERIA FOR JUDGING THE DAMAGE

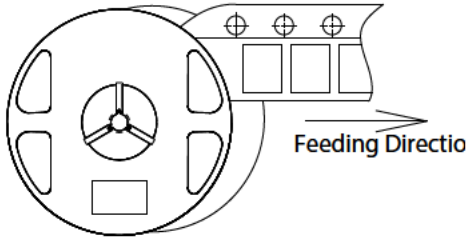
Item	Symbol	Test Conditions	Criteria for Judgement	
			Min.	Max.
Forward Voltage	VF	I <sub>F</sub> =150mA	-	U.S.L*)×1.1
Reverse Current	IR	V <sub>R</sub> =5V	-	U.S.L*)×2.0
Luminous Intensity	IV	I <sub>F</sub> =150mA	L.S.L**)×0.7	-

U.S.L.: Upper Standard Level

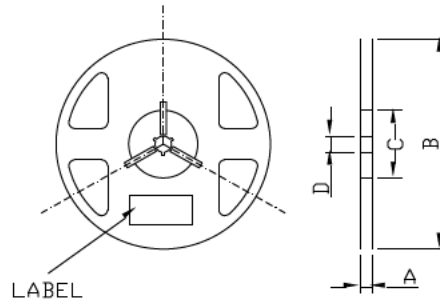
L.S.L.: Lower Standard Level

## Packaging Specifications

### • Feeding Direction

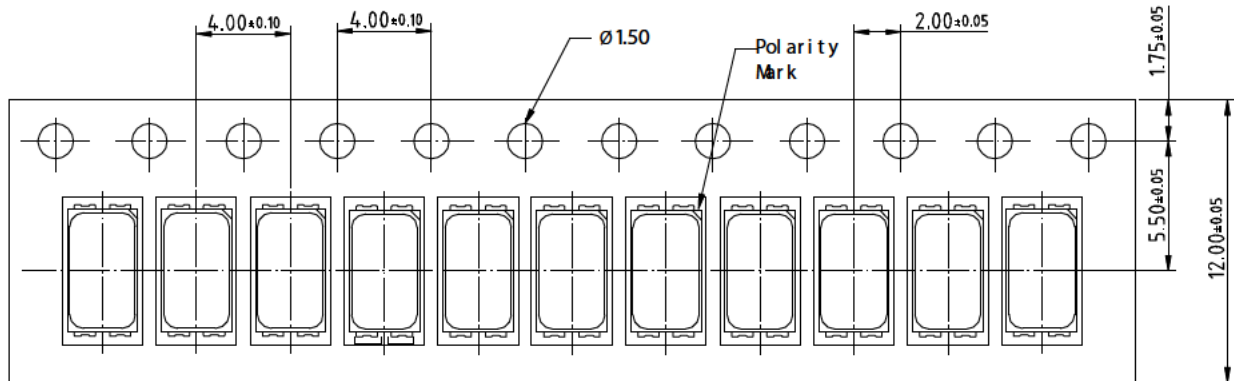


### • Dimensions of Reel (Unit: mm)

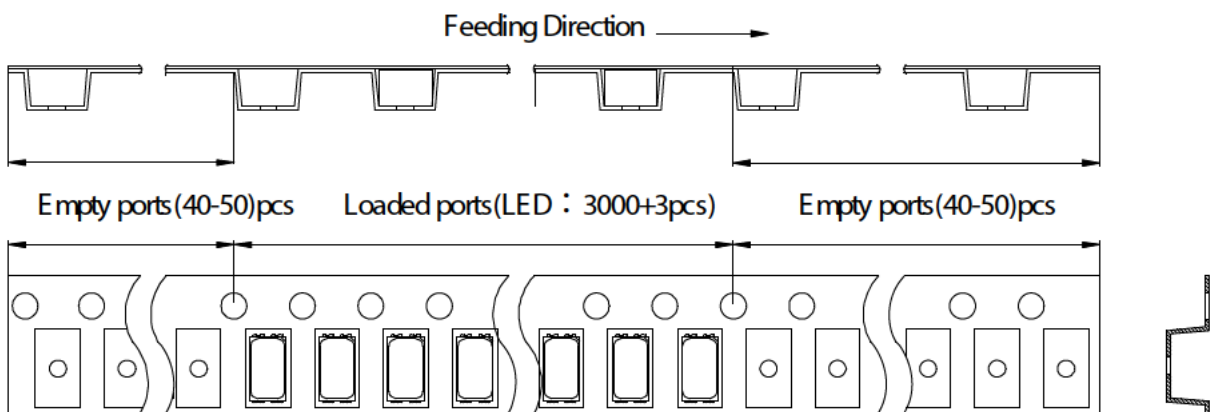


A	12± 0.1mm
B	179±1mm
C	58±1mm
D	13.5±0.5mm

### • Dimensions of Tape (Unit: mm)



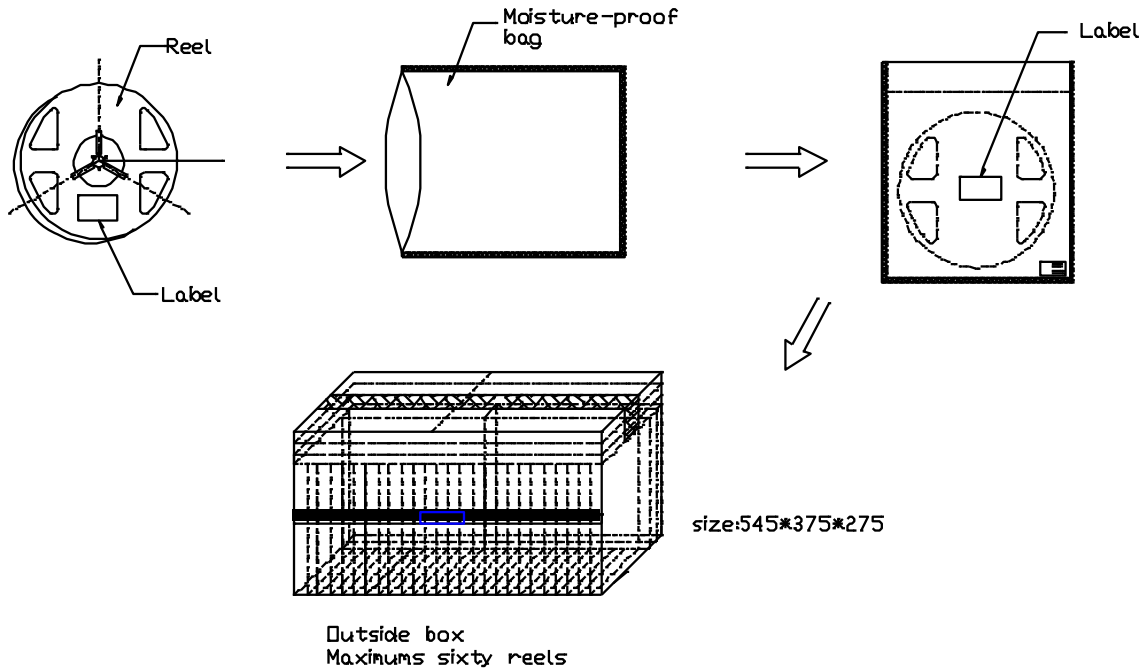
### • Arrangement of tape:



## NOTES

1. Empty component pockets are sealed with top cover tape;
2. The maximum number of missing lamps is two;
3. The cathode is oriented towards the tape sprocket hole in accordance with ANSI/EIA RS- 481 specifications.
4. 3,000 pcs/ Reel.

## Packaging specifications



• Label

PART NO:	
LOT NO:	
BIN CODE:	
IV:	VF: X/Y:
QTY:	PCS
DATE:	

## CAUTIONS

### Package specifications

Reeled products (3,000pcs) packed in a sealed moisture-proof bags along with a desiccant.

Sixty moisture proof bags maximum are put in each box(size: about 545mm x about 375mm x about 275 mm)

(Part No., Lot No., quantity should appear on the label on the moisture -proof bag, part No. And quantity should appear on the label on the cardboard box.)

### Storage conditions

#### Before opening the package:

The LEDs should be kept at 30 °C or less and 90%RH or less. The LEDs should be used within a year. When storing the LEDs, moisture proof packaging with absorbent material (silicagel) is recommended.

#### After opening the package:

The LEDs should be kept at 30°C or less and 70%RH or less. If unused LEDs remain, they should be stored in moisture proof packages, such as sealed containers with packages of moisture absorbent material (silicagel). It is also recommended to return the LEDs to the original moisture proof bag and to reseal the moisture proof bag again.